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PATENT

Docket No. JCLA8894

Date: 2-20-2002



ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing under 37 C.F.R. 1.53(b) is the patent application of

Inventor(s): HIROSHI SAWADA

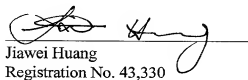
**For: SUBSTRATE CUTTING METHOD**

Enclosed are:

- (X) Specification in ( 25 ) pages.
- (X) ( 13 ) sheets of drawings.
- (X) Return prepaid postcard.

Note:

**THIS APPLICATION IS FILED UNSIGNED AND UNPAID**

  
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**CERTIFICATE OF MAILING BY "EXPRESS MAIL"**

**Docket No.** : JCLA8894  
**Inventor(s)** : HIROSHI SAWADA ;  
**For** : SUBSTRATE CUTTING METHOD  
**"Express Mail"** : EL 857834661 US  
**Mailing Label No.** :  
**Date of Deposit** : February 20, 2002

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 25 page(s); 13 Pages of Drawings;  
Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

*M. Chang*

Michelle Chang

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